

What is claimed is:

1. A liquid cooling system, comprising:

a pump for supplying a cooling liquid;

a heat-receiving jacket, being supplied with said cooling
5 liquid, for receiving heat from an electronic parts;

a radiator, being supplied with said cooling liquid passing
through said heat-receiving jacket, for radiation heat therefrom;
and

flow passages for circulating said cooling liquid in a route
10 passing through said radiator back to said pump, wherein:

an ion exchange bag, having a bag enclosing an ion exchange
resin therein, is disposed in a part of said route.

2. The liquid cooling system, as described in the claim
1, wherein:

15 the ion exchange bag, having the bag enclosing the ion
exchange resin therein, is held within a container, and said ion
exchange holder being exchangeable with the ion exchange bag is
provided in said container.

3. The liquid cooling system, as described in the claim
20 1, wherein:

said ion exchange bag are disposed within an inside or a
downstream of said radiator, and also in one of parts building
up the liquid cooling system in an upstream of said heat-receiving
jacket.

25 4. The liquid cooling system, as described in the claim
2, wherein:

said ion exchange bag or said ion exchange holder are disposed

within an inside or a downstream of said radiator, and also in one of parts building up the liquid cooling system in an upstream of said heat-receiving jacket.

5. An electronic apparatus, comprising:

5 a heat-generation element mounted on a substrate;

 a heat-receiving jacket, being thermally connected to said heat-generation element;

 a heat radiation jacket for radiating heat of a heated liquid supplied from said heat-receiving jacket;

10 a pump for circulating the liquid to those jackets; and

 a piping for connecting said pump and said both jackets, wherein:

 an ion exchange bag, having a bag enclosing ion exchange resin therein, is provided on way of said piping.

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